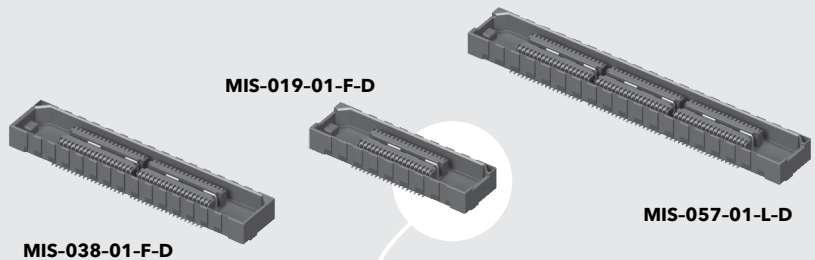


(0.635 mm) .025"

**MIS SERIES**

MIXED TECHNOLOGY SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MIS

Insulator Material:

Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over

50 μ " (1.27 μ m) Ni

Operating Temp Range:

-55 °C to +125 °C

Voltage Rating:

275 VAC/389 VDC

Max Cycles:

100

RoHS Compliant:

Yes

Board Mates:
MIT

Standoffs:
SO

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (019-057)

Board Stacking:

For applications requiring more than two connectors per board contact ipg@samtec.com

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

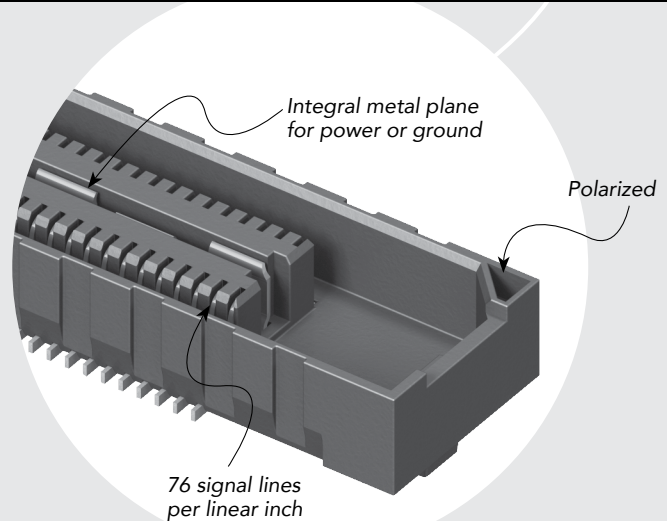


ALSO AVAILABLE

Contact Samtec

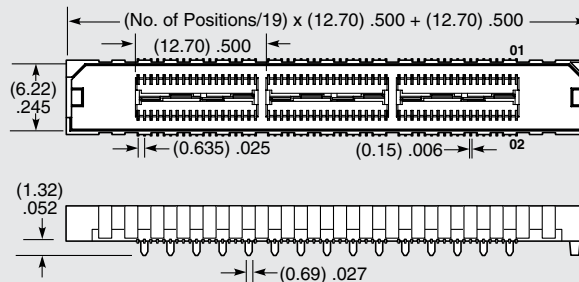
- 11 mm, 16 mm, 18.75 mm and 22 mm stack height
- 30 μ " (0.76 μ m) Gold
- Differential Pair and "Partitionable" (combine differential & single-ended banks in same connector) available.
- 76, 95, 114 and 133 positions per row

Note:
Some lengths, styles and options are non-standard, non-returnable.



MIS	POSITIONS PER ROW	01	PLATING OPTION	D	OPTION	PACKAGING
	-019, -038, -057 (38 total positions per bank)		-F = Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails -L = 10 μ " (0.25 μ m) Gold on Signal Pins and Ground Plane, Matte Tin on tails -C* = Electro-Polished Selective 50 μ " (1.27 μ m) min Au over 150 μ " (3.81 μ m) Ni on Signal Pins in contact area, 10 μ " (0.25 μ m) min Au over 50 μ " (1.27 μ m) Ni on Ground Plane in contact area, Matte Tin over 50 μ " (1.27 μ m) min Ni on all solder tails		-K = (7.00 mm) .275" DIA Polyimide film Pick & Place Pad	Leave blank for tray packaging -TR = Tape & Reel -FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

***Note:**
-C Plating passes 10 year MFG testing



Note: Rugged through-hole ground plane soldered to board (requires paste-over-hole, not press-fit) for added retention to PCB.

MIS LEAD STYLE	MATED HEIGHT*	
	-01	-02
-01	(5.00) .197	(8.00) .315

*Processing conditions will affect mated height. See SO Series for board space tolerances.